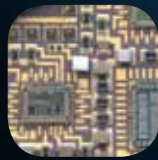


Microelectronics Packaging



TELEDYNE
MICROELECTRONIC TECHNOLOGIES

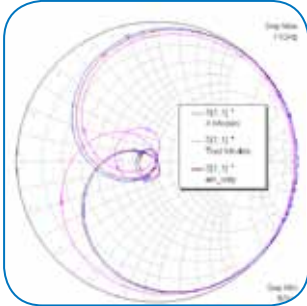
A Teledyne Technologies Company



**LEADER IN THE
SCIENCE AND ART OF
MICROELECTRONICS**

LEADER IN THE SCIENCE AND ART OF MICROELECTRONICS

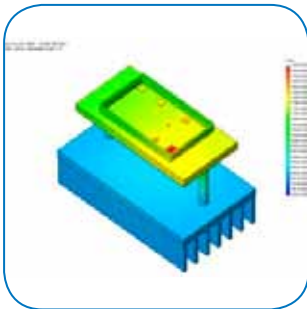
For over 45 years, we have led the industry in providing innovative, custom high-density, high-reliability microelectronics packaging solutions for the most demanding applications.



Optimize SWAP: Size, Weight, Power and Performance

Our dedicated team of scientists and engineers work with you to optimize your size, weight and performance requirements through:

- Circuit layout design
- Mechanical analysis
- Materials selection
- Thermal and power management analysis
- Power Integrity (PI) and Signal Integrity (SI) analysis



Services

At any phase of your design, we work with you to provide a cost effective, innovative packaging solution. Reliability and producibility are designed into every circuit, achieving a state-of-the-art quality product.

Advanced Technologies

We utilize a full array of advanced technologies to achieve optimal packaging for your circuit:

- WLP - Wafer Level Packaging
- CSP - Chip Scale Packaging
- SIP - System in Package
- MCM - Multichip Module
- MCA - Microwave Assembly
- Flip Chip/Flip Chip on Flex
- BGA/CGA - Ball/Column Grid Array
- Stud Bumping
- COB - Chip on Board
- SMT - Surface Mount Technology



Quality

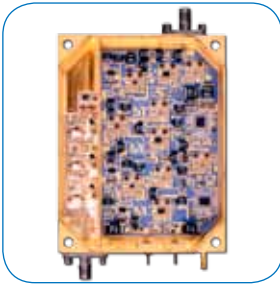
Every employee is committed to producing the highest quality product. We are a DoD DMEA Microelectronics Trusted Source, accredited for Microelectronics Packaging, Assembly and Test Services and maintain the highest level industry certifications:

- AS9100
- ISO 9001:2008
- MIL-PRF-38534, Class H and K



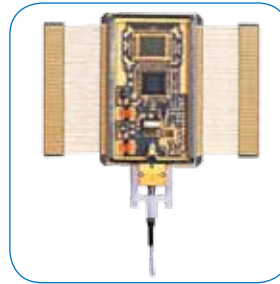
Contact our team to find out how we can help solve your toughest technology challenges.

Microelectronics Packaging Solutions



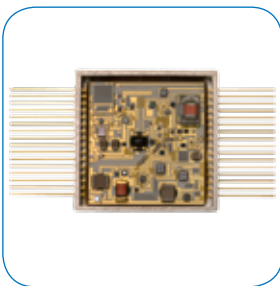
RF & Microwave

Low noise amplifiers, multi-throw switch assemblies, frequency doublers, up/down converters, detector log video amplifiers, successive detection log amplifiers. Optoelectronics to Microwave Integration



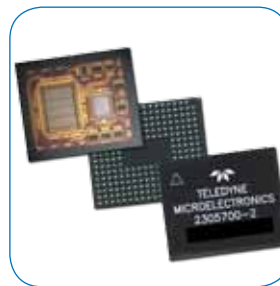
Optoelectronics

Fiber optic transmitters and receivers; detachable fiber connector or pigtailed fiber, auto alignment and laser welding, fiber polishing and lensing, BER testing. Optoelectronics to Microwave Integration



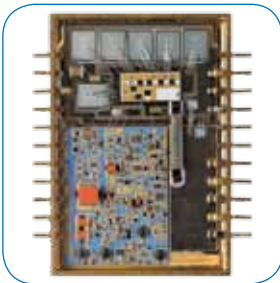
Space

Class K space level modules for spacecraft, satellites, launch vehicles, reentry vehicles, total dose radiation space Micro Dosimeter



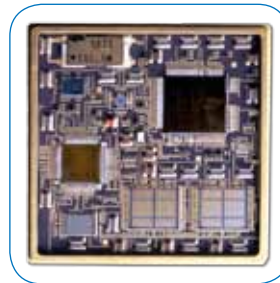
Mixed Signal

Signal processing, interface control modules, memory modules, armament control, avionics LED display modules



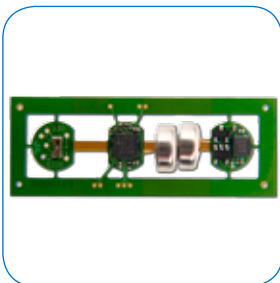
Power

Solid state power controllers, power converters, solid state switching



Secure Communications

FIPS 140-2, anti-tamper coatings, intrusion detection technologies, encryption protection



Medical

Cardiac rhythm management devices, neural and muscle stimulators, cochlear implants, drug infusion pumps, GI sensors, hearing aids, patient monitors



LED-Based Backlighting & Illuminators

High performance LED backlights, LED collimating illuminators and optics for LED light sources

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